

Blue are new market stabilizing/positive leaning info. Orange are new neutral/negative info.

Device	Company	Production Profile	Comments	
NAND	Overall NAND	3xxL continuing to ramp.	Capacity expansion pull-in on higher bit growth & AI demand.	
	Samsung	Vol.: 236L Ramp: 286L	- Granted export licensing into China for 2026 & likely 2027. - Xi'an upgrade to V8/V9; P4 NAND delayed to 2026, prioritizing DRAM.	
	Kioxia/Sandisk	Vol: 218L Ramp: 332L	- BiCS10 332L pulled into 2026 to support AI, cloud & enterprise demand. - WD divested NAND into Sandisk; CapEx increase to 3.7B in '25 and 4.1B '26	
	SK Hynix	Vol.: 321L	- Volume production of 321L QLC V9, shifting more capacity to support SSD - Granted export licensing into China for 2026 & likely 2027.	
	Micron	Vol.: 232L	- Singapore 10B construction started, ramp in 2028, >2x capacity than 10A/X	
	YMTC	Vol: 232L	- Started ramping 294L in Q1'25; +15% capacity expansion targeted for E'26 - Started construction of 3 rd fab, ramp to start in 2027; entity limits remain	
DRAM	Overall DRAM	HBM driving expanded DRAM spend to support AI; 4F ² development in progress		
	Samsung	Vol: 1b nm, Ramp: 1c nm	- Accelerating P5 construction for 2028 ramp. - Migrating NAND capacity to DRAM, volume at 1c in 2026 (200kwspm).	
	SK Hynix	Vol: 1b nm, Ramp: 1c nm	- Granted export licensing into China for 2026 & likely 2027. - M15X 1b production pulled into 1H'26, expanded construction start 1H'26 - Focusing spend on high bandwidth memory (1b/1c node) to meet AI demand	
	Micron	Vol: 1β nm Ramp: 1γ nm	- Groundbreaking on NY megafab complex (\$100B), expected ramp 2030. - Japan fab announce expansion (\$10B) into advanced DRAM, ramp 2H28. - To acquire PSMC P5 fab in Taiwan, conversion expected to ramp in 2027. - New Boise fab & Singapore assembly/test on track (2027)	
	ChangXin Mem. Tech. (CXMT)	Vol: 1y Ramp: 1z	- Fab2 (Hefei) ramping; not on entities list but nearing BIS node limit - Expanding Shanghai capacity, tools in 2H'26 with 2027 ramp	
	Other Memory	HBM 1x	- YMTC: new fab in Wuhan will have 50% dedicated to DRAM for HBM, 2027 - Nanya: new fab 2026 ramp expected - Winbond: accelerated Kaohsiung ramp of 16nm with tools moving in 2H26	
Foundry/Logic	Foundry/Logic	Leading & trailing nodes investment planned.	Advanced packaging is capacity limited.	
	≤16nm	TSMC	3nm	- FY'26 CapEx to \$54B; indicated expanded spend in 2026+ to support AI - Total US investment \$165B, potential additional \$100B & acquired new site - AZ (Fab1 4nm, 2025; F2 3nm, 2026; F3 2nm, 2027), Japan fab2 (6nm, 2027)
		Intel	4nm ≤14nm	- CapEx flat; Ohio TBD; CHiPs grant converted to U.S. equity stake - AZ 18A production ramping but no major outside customer
		Samsung	3nm GAA	- Reduced CapEx in '25. Taylor TX construction resumed, ops target 2026. - Yongin fab complex delays, target building 5 logic fabs in 20 years (\$230B)
		Rapidus	2nm GAA	- Production goal for 2027 accelerating ramp, \$3-4B CapEx '25 → ~\$8B 2026. - Announced new 1.4nm Hokkaido fab to start construction 2027.
		GlobalFoundries	14nm	- Malta new fab planned, timing TBD.
		SMIC	<14nm	- Delivering 7/5nm to Chinese chipmakers to circumvent US restrictions
	≥20nm	TSMC	22/28nm 12/16nm	- Japan Fab 23 P2 considering migrating to more advanced nodes (3nm). - Dresden JV fab (target tool move-in 2H26, ramp 2027-end)
		UMC	28nm	- YoY CapEx flat, Singapore production pushed to 2026
		SMIC	28nm	- Continuing high spending level with \$8B+ forecast for 2026
		Powerchip	>28nm	- Tongluo site to be acquired by Micron; Technology license sale to Tata (India)
		GlobalFoundries	28nm, FDSOI	- Announced 2x capacity expansion of Dresden fab to be completed by 2032. - Reiterated ST collaboration hold
		Other	>28nm	- US: TI SM1 ramping; announced additional fabs for Sherman (SM3&4). - China: CanSemi (Guangzhou, +40K wmp), Hua Hong (Wuxi, \$6.7B +30K), Wingsky (Shanghai, 45K), Zensemi (MEMS, Quangshou), CR Micro (Shenzhen) - Japan: Toshiba (P2 '26), slowed/inactive: Renesas; Rohm, Sanken, Sony. - Europe: ST (Crolles on hold); Infineon (Dresden, 2026) - India: Tata (delays to site construction, possibly pushed site ops to 2028)
	Packaging	TSMC	-	- \$5-10B (10-15% CapEx), to support AI demand - US Adv. packaging fabs accelerating using P6 site, possible 2027 tooling.
Intel			- Consolidating sites (closing Costa Rica); canceled Poland plan (2027).	
GlobalFoundries			- Adding adv. pkg & test expansion to Malta	
SK Hynix			- HBM fab in Indiana (2028) and \$13B site in Cheongju, expected ramp 2027.	
	OSAT		- Starting capacity add for adv. packaging to support excess TSMC demand	